

### REMARKS

Claims 9-15 are now present in the application and are presented for examination as a result of the withdrawal of claims 1-4 and 8 from consideration as being directed to a non-elected invention per the Notice of Non-compliant Amendment dated October 24, 2006. Accordingly, claims 1-4 and 8 are now cancelled and claims 5-7 are cancelled pursuant to a requirement for restriction.

In the previous Office Action, claims 1-4 and 8 were rejected under 35 U.S.C. 103(a) as being unpatentable over *Glenn et al.* in view of *Uchikoba*.

Independent claim 9, which is newly presented for examination, now recites "a co-fired, multi-layer laminate ceramic structure comprising: a plurality of stacked co-fired layers of a predetermined type of ceramic material including metallization in predetermined patterns on and through said layers; a plurality of exposed electrical conductors including leads located at predetermined locations on said plurality of stacked layers; said conductors being comprised of a metal paste including one or more additives to promote adhesion to said layers of ceramic material; a bonding metal layer located on top of said exposed electrical conductors at the locations of said leads and being of said same metal as said conductors, however, devoid of said one or more additives so as to enhance bondability of the leads thereon; and, wherein the leads are bonded to said bonding metal layer at said predetermined locations."

Claim 1, as originally presented, included the recitation "said conductors being of a metal which includes one or more additives to promote adhesion to said ceramic layer on which said conductors are deposited". In the previous rejection of claims 1-4 and 8, under 35 U.S.C. 103(a) as being unpatentable over *Glenn et al.* in view of *Uchikoba*, the Examiner stated that "Glenn does not explicitly teach that the bonding metal layer being of the same metal as the conductors, however, devoid of the one or more additives.

*Uchikoba* teaches (Figure 1A-1C) forming a conductive electrode 43 that is formed of gold and nickel and connected to a gold bond (31, no nickel) in the structure of forming a semiconductor device package”.

In reviewing the *Uchikoba* reference, it is to be noted that at column 6, lines 46-50, it states “In a gold plating step as shown in Figure 1B, nickel is plated about 2 to 3 $\mu$ m thick as a roughly plated layer over the surface conductive layer 42 (sintered conductor of silver) on the ceramic multi-layer substrate 40, and then gold is plated thereon to form a mounted electrode 43 having a gold film.”

Applicants’ invention in newly presented claim 9 now claims a multi-layer laminate ceramic structure wherein the conductors are comprised of a metal paste including one or more additives to promote adhesion to the layers of ceramic material. Moreover, in newly submitted dependent claim 11, the conductors are recited as being comprised of a gold paste including additives selected from a group of materials including copper, bismuth and glass. It is submitted that this tether structure is different from a layer of nickel plated with a gold film.

It is submitted that applicants’ invention as now claimed is neither shown nor described by either *Glenn et al.* or *Uchikoba*, taken either singly or in combination, nor would such be obvious without hindsight provided by applicants’ own disclosure and therefore newly presented independent claims 9 and 14 are deemed to be in condition for allowance and dependent claims 11-13 and 15 are deemed allowable by virtue of their dependency.

Further and favorable action is therefore requested.

Should there be any outstanding matters that need to be resolved in the present application, the Examiner is respectfully requested to contact the undersigned at the telephone number of the undersigned below.

If necessary, the Commissioner is hereby authorized in this, concurrent, and future replies to charge payment or credit any overpayment to Deposit

Application No. 10/786,125  
Amendment dated October 31, 2006  
Reply to Office Action dated October 24, 2006

Docket No.: 1215-0506P

Account No. 02-2448 for any additional fees required under 37.C.F.R. §§1.16 or 1.14; particularly, extension of time fees.

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Respectfully submitted,

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